

FEATURES

- Fast switching device ($t_{rr} < 4.0\text{ns}$)
- Surface mount device type
- Moisture sensitivity level 1
- Matte Tin (Sn) lead finish with Nickel (Ni) underplate
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

MECHANICAL DATA

- Case: Bend lead SOD-123 small outline plastic package
- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : $260^{\circ}\text{C}/10\text{s}$
- Polarity: Indicated by cathode band
- Weight: $10 \pm 0.5\text{ mg}$
- Marking Code: T4



SOD-123



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	VALUE	UNIT
Power dissipation	P_D	350	mW
DC blocking voltage	V_R	100	V
Repetitive peak reverse voltage	V_{RRM}	100	V
Work peak reverse voltage	V_{RWM}	100	V
RMS reverse voltage	$V_{R(RMS)}$	70	V
Repetitive peak forward current	I_{FRM}	300	mA
Mean forward current	I_O	150	mA
Non-repetitive peak forward surge current @ $t=1\text{ ms}$ @ $t=10\text{ ms}$	I_{FSM}	2.0 1.0	A
Thermal resistance (Junction to Ambient) (Note 1)	$R_{\theta JA}$	357	$^{\circ}\text{C}/\text{W}$
Junction and storage temperature range	T_J, T_{STG}	-65 to +150	$^{\circ}\text{C}$

PARAMETER	SYMBOL	MIN	MAX	UNIT
Forward voltage	V_F	-	0.715	V
		-	0.855	
		-	1.000	
		-	1.250	
Reverse leakage current	I_R	-	25	nA
		-	2.5	μA
		-	30	μA
		-	50	μA
Junction capacitance	C_J	-	2.0	pF
Reverse recovery time	t_{rr}	-	4.0	ns

Notes: 1. Valid provided that terminals are kept at ambient temperature

Notes: 2. Test Conditions : $I_F=10mA$, $I_R=10mA$, $R_L=100\Omega$, $I_{RR}=1mA$

RATINGS AND CHARACTERISTICS CURVES ($T_A=25^\circ C$ unless otherwise noted)

Fig.1 Typical Forward Characteristics

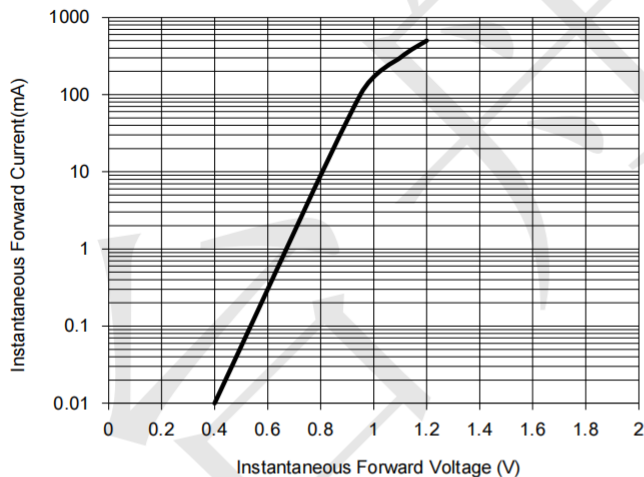
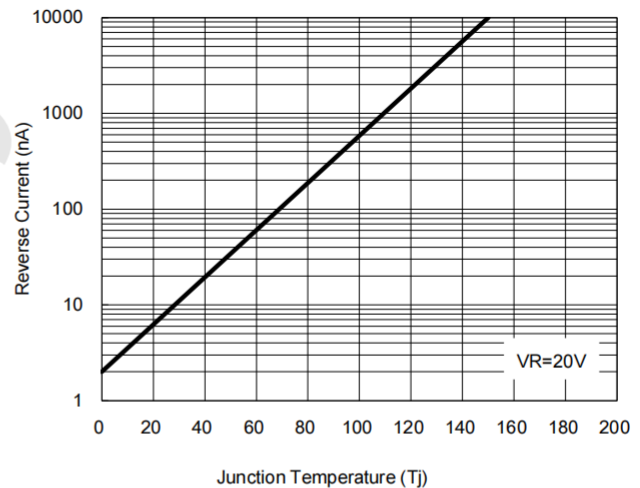
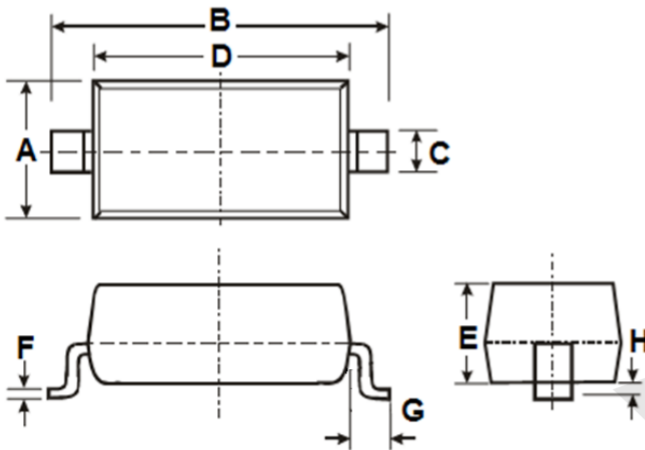


Fig. 2 Reverse Current vs Junction Temperature



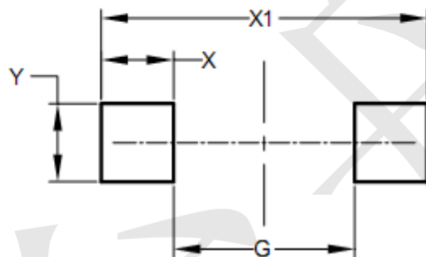
DIMENSIONS

SOD-123



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.40	1.80	0.055	0.071
B	3.55	3.85	0.140	0.152
C	0.45	0.70	0.018	0.028
D	2.55	2.85	0.100	0.112
E	0.95	1.35	0.037	0.053
F	0.05	0.15	0.002	0.006
G	0.50 REF		0.02 REF	
H	-	0.10	-	0.004

SUGGESTED PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)
	Min	Min
G	2.25	0.089
X	0.90	0.035
X1	4.05	0.159
Y	0.95	0.037